

TOSHIBA FIELD EFFECT TRANSISTOR SILICON N CHANNEL MOS TYPE (L<sup>2</sup>-π-MOSV)

# 2SK2232

HIGH SPEED, HIGH CURRENT SWITCHING APPLICATIONS  
 CHOPPER REGULATOR, DC-DC CONVERTER AND MOTOR DRIVE APPLICATIONS

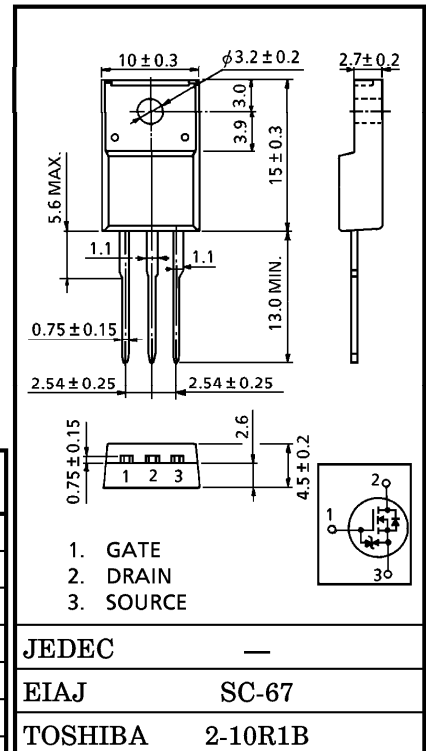
INDUSTRIAL APPLICATIONS

Unit in mm

- 4 V Gate Drive
- Low Drain-Source ON Resistance :  $R_{DS(ON)} = 36 \text{ m}\Omega$  (Typ.)
- High Forward Transfer Admittance :  $|Y_{fs}| = 16 \text{ S}$  (Typ.)
- Low Leakage Current :  $I_{DSS} = 100 \mu\text{A}$  (Max.) ( $V_{DS} = 60 \text{ V}$ )
- Enhancement-Mode :  $V_{th} = 0.8 \sim 2.0 \text{ V}$   
 ( $V_{DS} = 10 \text{ V}, I_D = 1 \text{ mA}$ )

MAXIMUM RATINGS ( $T_a = 25^\circ\text{C}$ )

CHARACTERISTIC	SYMBOL	RATING	UNIT
Drain-Source Voltage	$V_{DSS}$	60	V
Drain-Gate Voltage ( $R_{GS} = 20 \text{ k}\Omega$ )	$V_{DGR}$	60	V
Gate-Source Voltage	$V_{GSS}$	$\pm 20$	V
Drain Current	DC	$I_D$	25 A
	Pulse	$I_{DP}$	100 A
Drain Power Dissipation ( $T_c = 25^\circ\text{C}$ )	$P_D$	35	W
Single Pulse Avalanche Energy**	$E_{AS}$	156	mJ
Avalanche Current	$I_{AR}$	25	A
Repetitive Avalanche Energy*	$E_{AR}$	3.5	mJ
Channel Temperature	$T_{ch}$	150	$^\circ\text{C}$
Storage Temperature Range	$T_{stg}$	$-55 \sim 150$	$^\circ\text{C}$



Weight : 1.9 g

THERMAL CHARACTERISTICS

CHARACTERISTIC	SYMBOL	MAX.	UNIT
Thermal Resistance, Channel To Case	$R_{th(ch-c)}$	3.57	$^\circ\text{C} / \text{W}$
Thermal Resistance, Channel To Ambient	$R_{th(ch-a)}$	62.5	$^\circ\text{C} / \text{W}$

Note ;

- \* Repetitive rating ; Pulse Width Limited by Max. junction temperature.
- \*\*  $V_{DD} = 25 \text{ V}, T_{ch} = 25^\circ\text{C}$  (initial),  $L = 339 \mu\text{H}, R_G = 25 \Omega, I_{AR} = 25 \text{ A}$

**This transistor is an electrostatic sensitive device.  
 Please handle with caution.**

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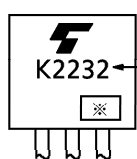
ELECTRICAL CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT	
Gate Leakage Current	IGSS	VGS = ±16 V, VDS = 0 V	—	—	±10	μA	
Drain Cut-off Current	IDSS	VDS = 60 V, VGS = 0 V	—	—	100	μA	
Drain-Source Breakdown Voltage	V(BR)DSS	ID = 10 mA, VGS = 0 V	60	—	—	V	
Gate Threshold Voltage	Vth	VDS = 10 V, ID = 1 mA	0.8	—	2.0	V	
Drain-Source ON Resistance	RDS(ON)	VGS = 4 V, ID = 12 A	—	0.057	0.08	Ω	
		VGS = 10 V, ID = 12 A	—	0.036	0.046		
Forward Transfer Admittance	Yfs	VDS = 10 V, ID = 12 A	10	16	—	S	
Input Capacitance	Ciss	VDS = 10 V, VGS = 0 V f = 1 MHz	—	1000	—	pF	
Reverse Transfer Capacitance	Crss		—	200	—		
Output Capacitance	Coss		—	550	—		
Switching Time	Rise Time	tr		—	20	—	ns
	Turn-on Time	ton		—	30	—	
	Fall Time	tf		—	55	—	
	Turn-off Time	t <sub>off</sub>		VIN : tr, tf < 5 ns Duty ≤ 1%, tw = 10 μs	—	130	
Total Gate Charge (Gate-Source Plus Gate-Drain)	Qg	VDD ≐ 48 V, VGS = 10 V ID = 25 A	—	38	—	nC	
Gate-Source Charge	Qgs		—	25	—		
Gate-Drain (“Miller”) Charge	Qgd		—	13	—		

SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Continuous Drain Reverse Current	IDR	—	—	—	25	A
Pulse Drain Reverse Current	IDRP	—	—	—	100	A
Diode Forward Voltage	VDSF	IDR = 25 A, VGS = 0 V	—	—	-1.8	V
Reverse Recovery Time	t <sub>rr</sub>	IDR = 25 A, VGS = 0 V	—	50	—	ns
Reverse Recovery Charge	Q <sub>rr</sub>	dIDR / dt = 50 A / μs	—	35	—	nC

MARKING

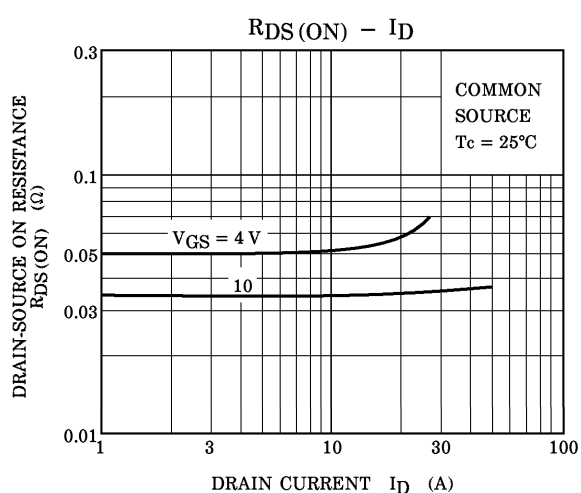
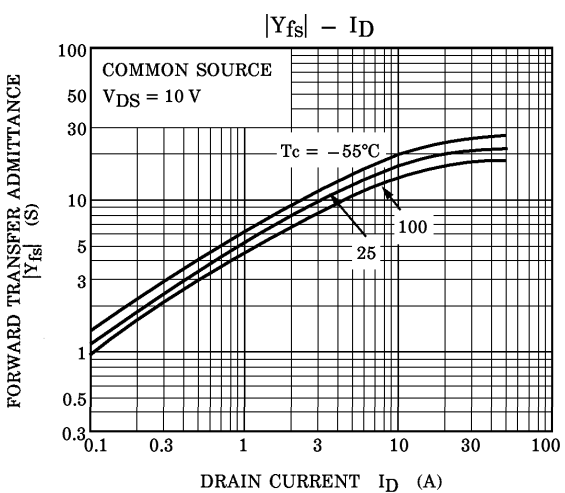
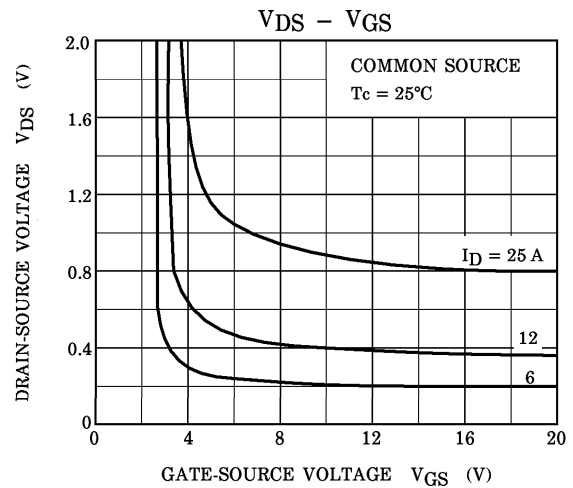
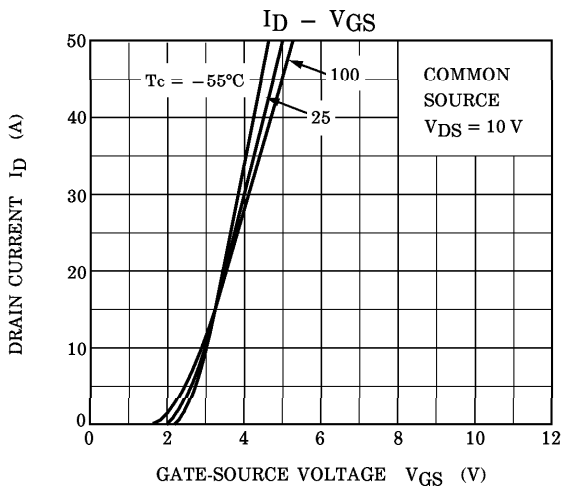
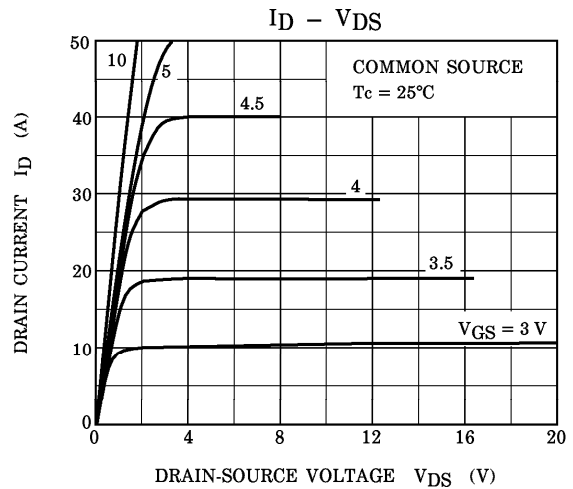
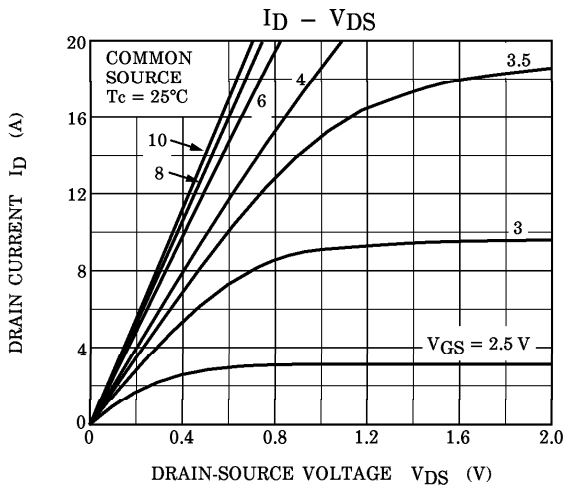


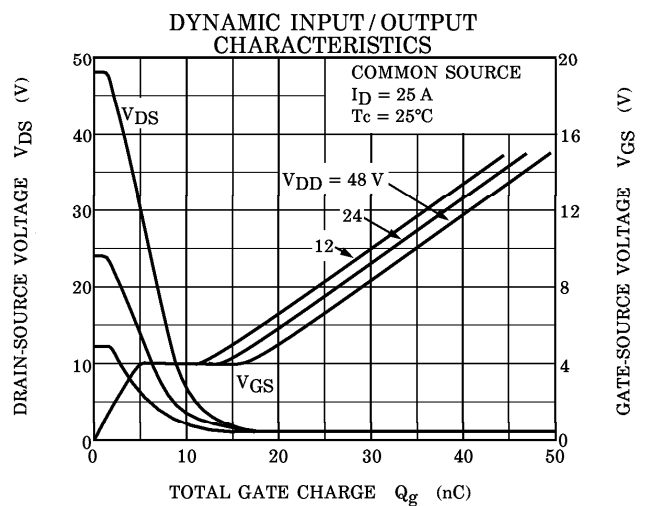
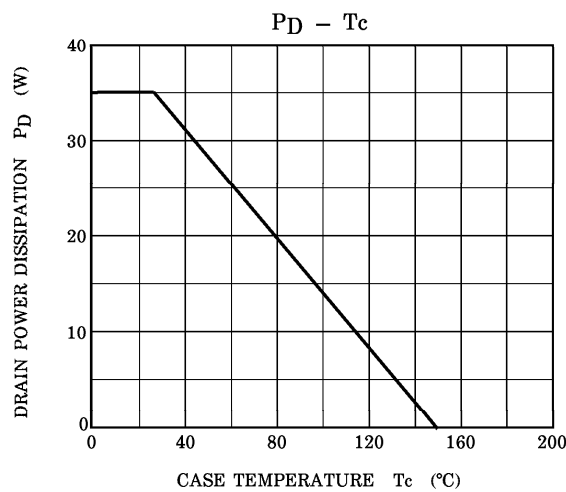
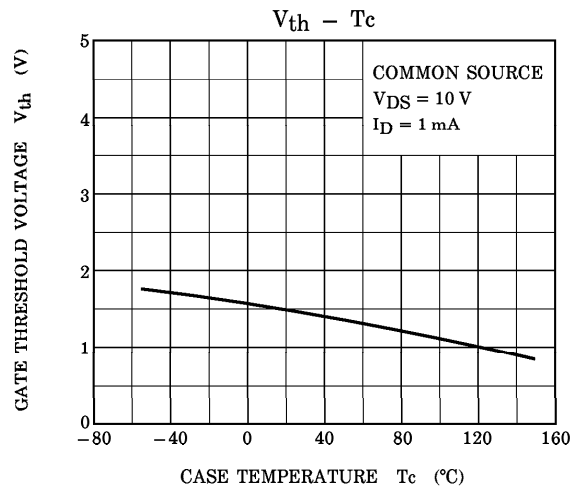
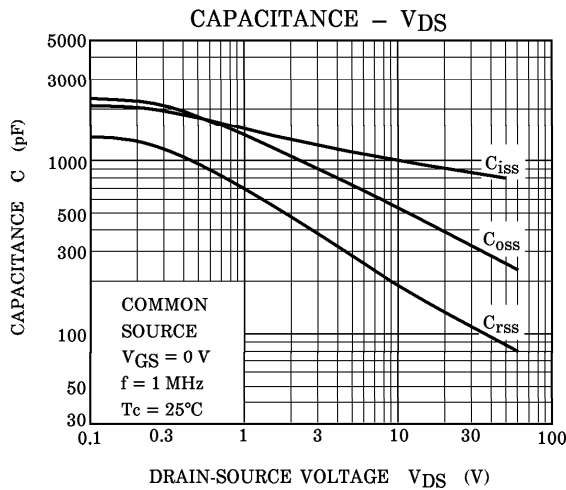
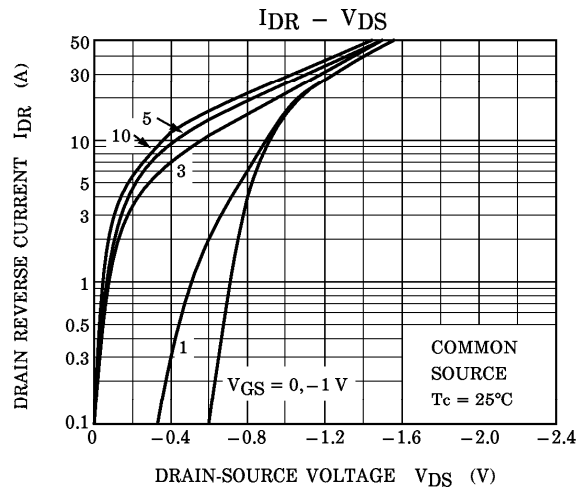
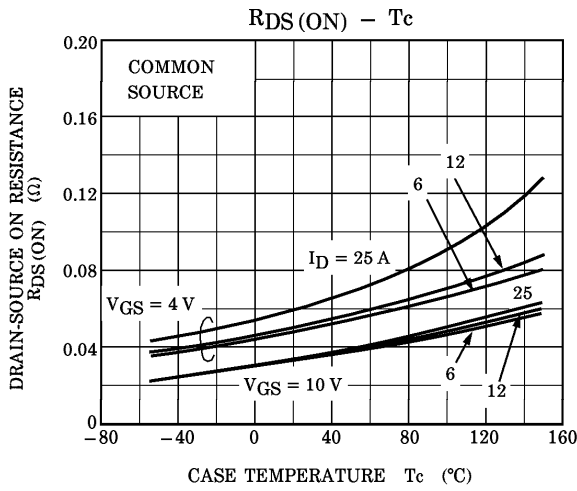
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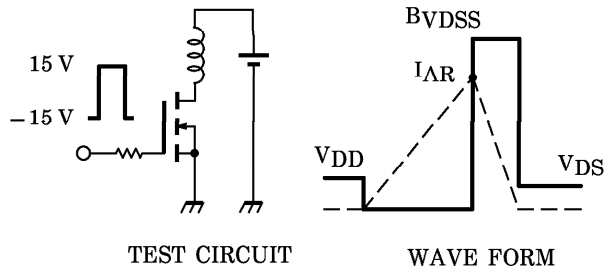
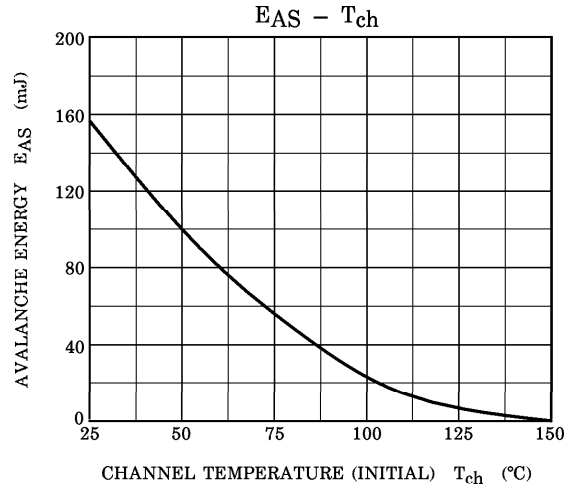
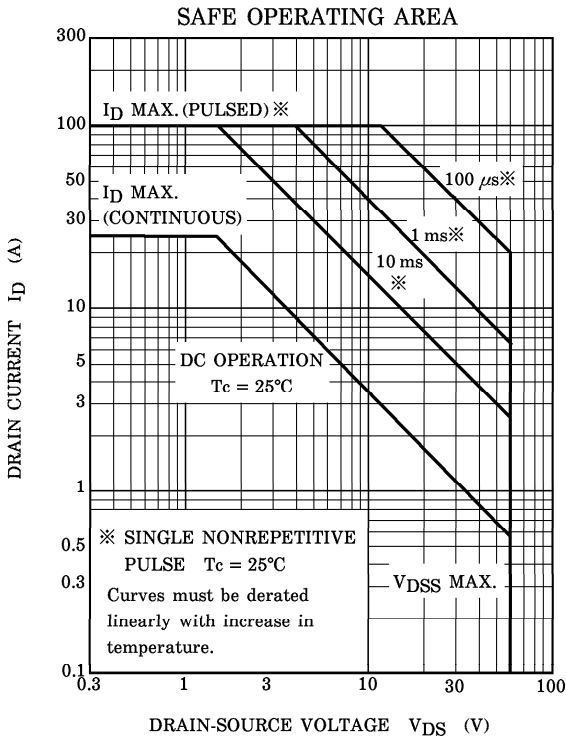
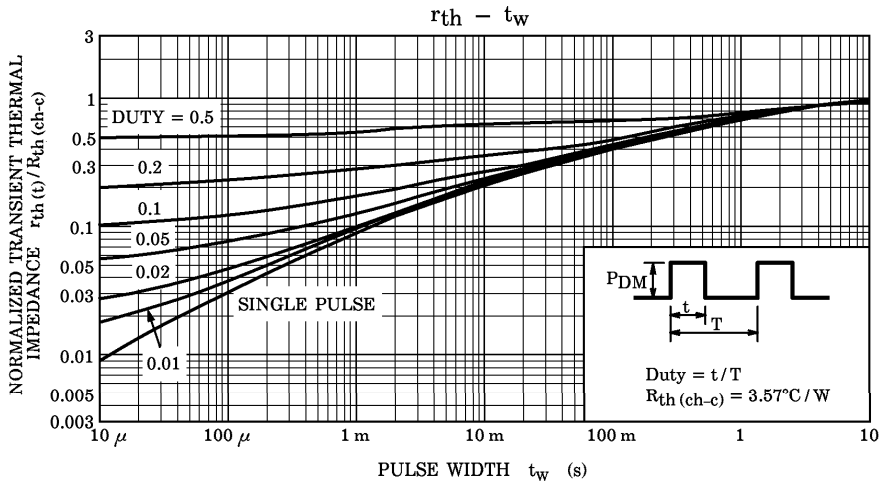
※ Lot Number

□ □ — Month (Starting from Alphabet A)

— Year (Last Number of the Christian Era)







Peak  $I_{AR} = 25$  A,  $R_G = 25 \Omega$   $E_{AS} = \frac{1}{2} \cdot L \cdot I^2 \cdot \left( \frac{BVDSS}{BVDSS - V_{DD}} \right)$   
 $V_{DD} = 25$  V,  $L = 339 \mu H$